

PIN ADAPTER FOR AIR BEARING SURFACE (ABS) LAPPING AND  
METHOD FOR USING THE SAME

ABSTRACT

A system is provided for measuring a head during a lapping process. First provided is a wafer including at least one head each having an electrical lapping guide (ELG), a plurality of wafer contacts in electrical communication with the ELG, and a closure formed thereon defining a slot in which the wafer contacts are positioned. Also included is a lapping cable coupled to a testing device. The lapping cable includes a plurality of lapping cable contacts. An adapter includes a plurality of adapter contacts in electrical communication with the lapping cable contacts. The adapter contacts are removably positionable in electrical communication with the wafer contacts for measuring the head during a lapping process.

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